

2169 Soldering Flux

Organic, Water Soluble, Liquid Flux

Product Description

Kester 2169 Soldering Flux is a halide-free organic flux that is designed for semiconductor component lead tinning and PCB soldering. This flux provides good activity on metals such as Nickel Iron (Alloy 42), nickel plate and copper alloy. Proper use of 2169 results in a non-porous solder coating in which a continuous, uniform metallurgical bond is formed with the base metal. The unique activity and surface tension properties of the flux minimize soldering defects such as icicles, bridging, excessive solder or white residues in component dipping.

X-ray analysis of non-hermetic, plastic packages have shown that the trim and form operation creates internal hairline cracks in the package which might allow flux or other contamination to seep inside because of the thermal expansion stresses encountered during soldering. Further research has shown the halide residues from organic halide fluxes in the presence of moisture can migrate along the interface between the molding compound and the lead frame surface to corrode the wire bonding pads. 2169 contains no chlorides or bromides, or other additives, which can cause internal package corrosion that is detrimental to component reliability. Therefore, the use of 2169 ensures component reliability.

Performance Characteristics:

- High activity
- Halide-free
- Improves soldering performance

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2015/863 for the stated banned substances.

Physical Properties

Specific Gravity: 0.919 ± 0.005

Anton Paar DMA 35 @ 25 °C

Percent Solids (typical): 27

Tested to J-STD-004, IPC-TM-650, Method 2.3.34

Acid Number (typical): 122 mg KOH/g of flux

Tested by potentiometric titration

pH (10% solution, typical): 2.8

Mettler-Toledo MA235 pH/Ions Analyzer

Surface Tension (typical): 23.0 dynes/cm

Kruss Digital Tensometer @ 25 °C

Halide Content: None Detected

Thinner: Kester 4169

Flux Application

2169 is designed for use in high throughput, automated wave or dip soldering operations as well as manual solder dipping. Both plastic and ceramic packages can be solder coated using this flux, especially when minimal splattering is desired.

Process Considerations

The optimum preheating temperature is 95 to 105 °C (203 to 221 °F), as measured on the component leads. Sufficient preheating is needed after fluxing to evaporate the solvent vehicle, bring the flux to its optimum activation state and prevent thermal shock on components. Lead materials normally become heavily oxidized as a result of heat encountered during the wire bonding and molding operations for plastic packages. Proper precleaning of components prior to soldering is necessary to remove the oxide layer so that soldering defects are minimized and consistent soldering results are obtained. Care should be taken to minimize or prevent water drag-in from the precleaning station as excessive water can be detrimental to the activity and surface tension properties of the flux. Solder temperature of 245 to 255 °C (473 to 491 °F) is generally recommended for Sn63Pb67 alloy.

Above information is a guideline and it is advisable to note that the optimum process parameters depend on soldering equipment design, component fixture design and the type of components to be solder coated. A design of experiment is recommended to be done to optimize the soldering process.

Flux Control

Measures should be taken to minimize or prevent water drag-in from the precleaning station as excessive water can be detrimental to the activity and surface tension properties of the flux. Checking of the specific gravity at regular intervals is essential and addition of the appropriate amount of Kester 4169 Thinner will assure consistent, controlled soldering results. The use of improper thinner may cause a separation of the constituents or affect other performance properties of the flux.

Cleaning

No neutralizer, saponifiers or detergents are necessary in the water wash system for complete removal of flux residues. Deionized water may be used for cleaning. It is not recommended to use high mineral content tap water. The optimum water temperature is 49 to 60 °C (120 to 140 °F), although lower temperatures may be sufficient.

Recycling Services

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams.

Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area or [link here](#).



Storage, Handling and Shelf Life

2169 is flammable. Store away from sources of ignition. Shelf life is 1 year from date of manufacture when handled properly and held at 10 to 25 °C (50 to 77 °F).

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at this [link](#).

Contact Information

To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

North America 109 Corporate Blvd. South Plainfield, NJ 07080, USA 1.800.253.7837	Europe Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400	Asia Pacific 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong 852.3190.3100
--	---	--

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, indirect, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "R" and "TM" are registered trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.